

Abstract

The invention relates to an arrangement for a junction between a microstripline and a waveguide, comprising

- a microstripline (ML) which is fitted on the upper face of a dielectric substrate (S),
- a waveguide which is fitted on the upper face of the substrate (S) and has an opening (OB) on at least one end surface and has a structure (ST) which is in the form of a step or steps in the area of the opening (OB) on one side wall and is conductively connected in at least one part (ST1) to the microstripline (ML), and wherein one side wall of the waveguide is a metallized layer (LS) formed on the substrate (S),
- a cutout (A) which is formed in the metallized layer (LS) and into which the microstripline (ML) projects,
- rear-face metallization (RM) which is formed on the rear face of the substrate (S), and
- electrically conductive via holes (VH) between the metallized layer (LS) on the upper face of the substrate (S) and the rear-face metallization (RM), which surround the cutout (A).

(Figure 4)



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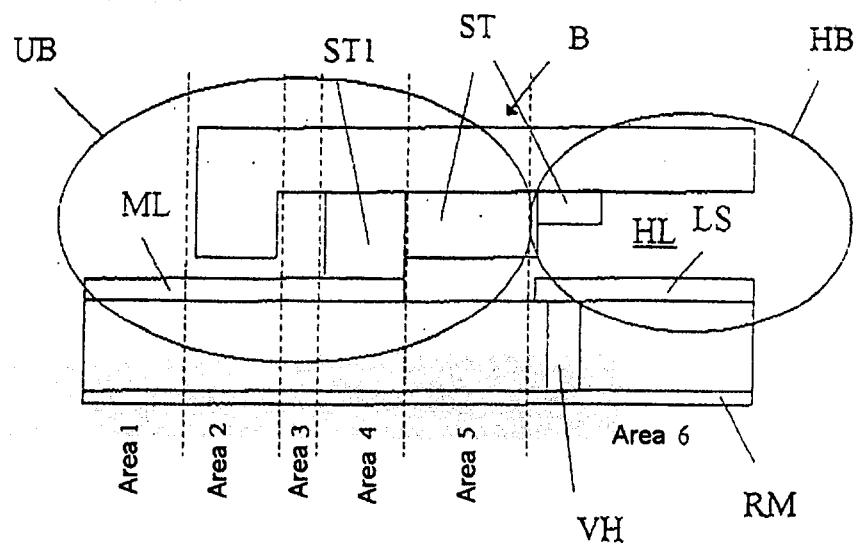


Fig. 4